



All Mini-Circuits products are manufactured under exacting quality assurance and control standards, and are capable of meeting published specifications after being subjected to any or all of the following physical and environmental test.

Specification	Test/Inspection Condition	Reference/Spec
Operating Temperature	-45° to 85°C Ambient Environment	Individual Model Data Sheet
Storage Temperature	-65° to 150° C Ambient Environment	Individual Model Data Sheet
Thermal Shock	-65° to 150°C, 500 Cycles	MIL-STD-883E, Method 1010.7
Autoclave	15 psig, 100% RH, 121°C, 96 hours	JESD22-A102-C, Condition C
Solderability	10X Magnification	J-STD-002, Para 4.2.5, Test S, 95% Coverage
Solder Reflow Heat	Pb-Free Process: 260°C peak	J-STD-020C, Table 4-1, 4-2 and 5-2; Figure 5-1
Moisture Sensitivity: Level 1	Bake at 125°C for 24 hours Soak at 85°C/85% RH for 168 hours, Reflow 3 cycles at 260°C peak	J-STD-020C
Marking Resistance to Solvents	Solution A, C and D followed by 3 reflow cycles at 260°C peak	MIL-STD-202F, Method 215J
Lead Integrity	Tension - Cond. A Bonding Stress - Cond. B1	MIL-STD-883E, Method 2004.5